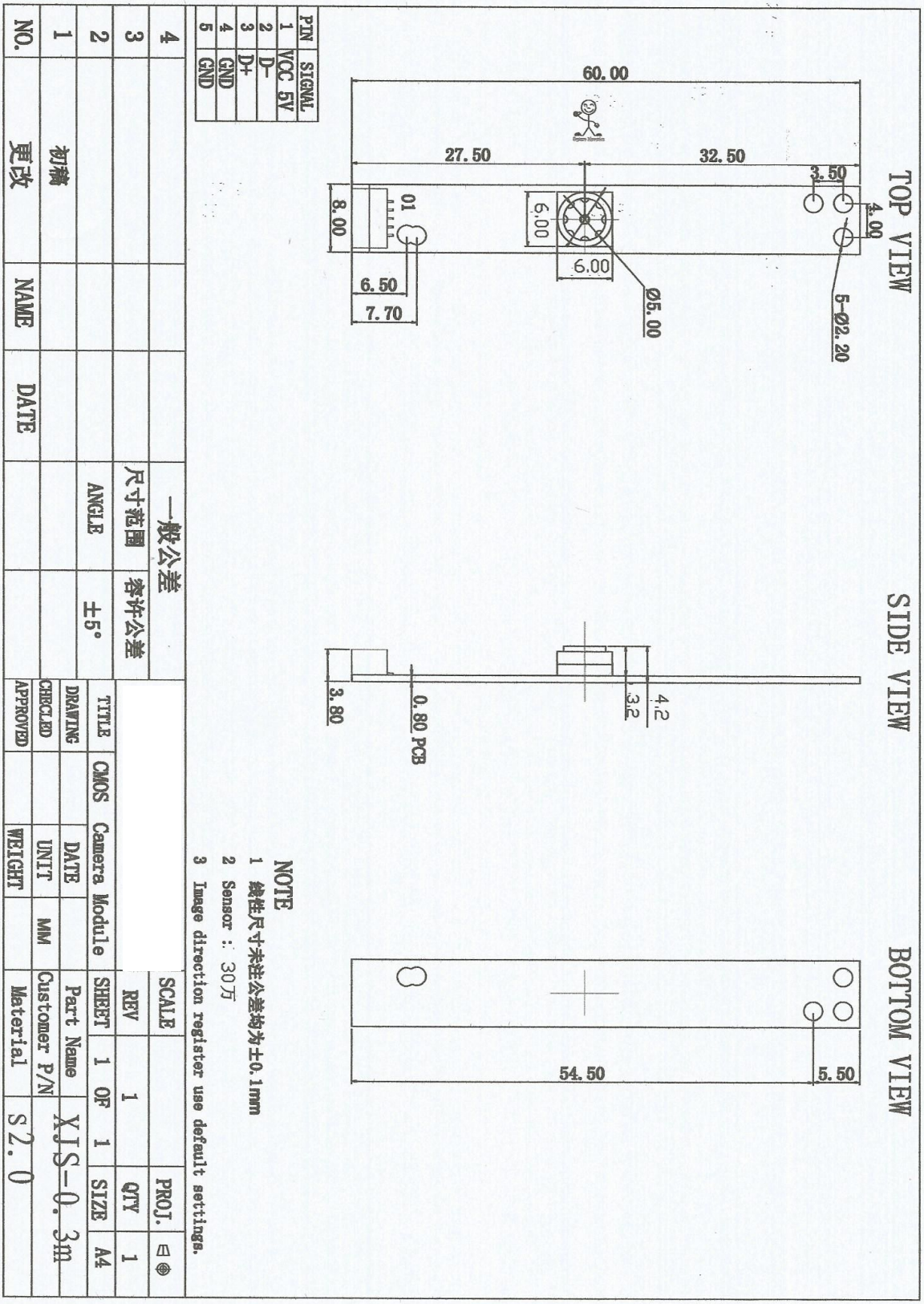
1. Key Specifications

Module No.	XJS-0.3m s2.0
Module Size	60mm × 8mm × 4.2mm
Temperature (Operation)	-20° to 70°CC
Temperature (Stable Image)	0° to 50°CC
Assembly technique	SMT (ROSH)
Focus	Fixed
Object distance	15CM-130CM
Resolution	600LW/PH (Center)
PCB printing ink	black
interface	USB 2.0
Power	USB bus power
Power consumption	110mW （VGA）; 130 mW （UXGA）;
Operating system request	Windows 2000\ Windows XP/7/8 安卓
Package	Anti-electrostatic tray
Certifications	FCC and CE
Sensor Type	CMOS (1/9”)
Active Array Size	640*480@fps
Sensitivity	TBD
Pixel Size	2.5μm x 2.5μm
Maximum Image Transfer Rate	30 fps for UXGA;
S/N Ratio	TBD
Dynamic Range	TBD
Package	CSP,Bare Die
Lens Type	
Lens Construction	2P+IR
F/No	4.0mm
EFL	2.8mm
BFL(Optical)	4.8mm
FOV	62°
TV Distortion	<1.0%
Relative Illumination (Sensor)	70%
IR Filter	650±10nm
DSP Type	
AGC/AEC/Whiter balance	Auto
Output Formats	USB suspend out
Fixed Pattern Noise	
Package	< 0.03% of
	$V_{PEAK-TO-PEAK}$

2. Module Mechanical Dimension



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